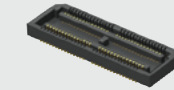


LSH-030-01-G-D-A



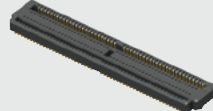
LSH-010-01-G-D-A



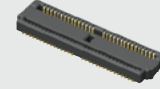
LSH-050-01-G-D-A



LTH-050-01-G-D-A



LTH-030-01-G-D-A



LTH-010-01-G-D-A



(0.50 mm) .0197"

LTH, LSH SERIES

# LOW-PROFILE BLADE AND BEAM

LTH Mates with:

LSH

LSH Mates with:

LTH

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?LTH](http://www.samtec.com?LTH) or [www.samtec.com?LSH](http://www.samtec.com?LSH)

**Insulator Material:**

Liquid Crystal Polymer

**Terminal Material:**

Phosphor Bronze

**Contact Material:**

BeCu

**Plating:**

Au over 50 μ" (1.27 μm) Ni

**Current Rating:**

2.6 A per pin

(2 pins powered)

**Operating Temp Range:**

-55 °C to +125 °C

**RoHS Compliant:**

Yes

## PROCESSING

**Lead-Free Solderable:**

Yes

**SMT Lead Coplanarity:**

(0.10 mm) .004" max

**Board Stacking:**

For applications requiring more than two connectors per board, contact [ipg@samtec.com](mailto:ipg@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(2.31) .091

\*Processing conditions will affect mated height.

**Note:** Some lengths, styles and options are non-standard, non-returnable.

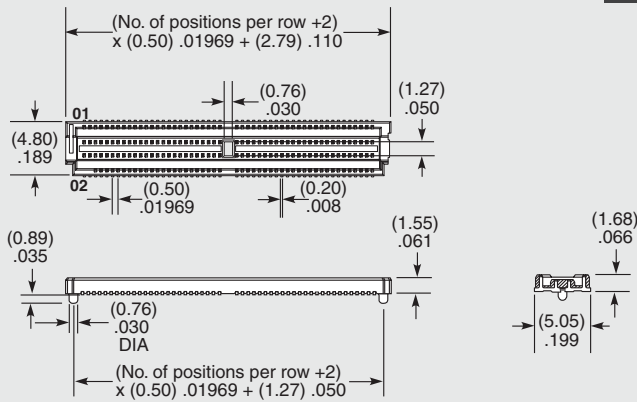


-010, -020, -030, -040, -050

-G  
= 10 μ" (0.25 μm) Gold

-K  
= (5.50 mm) .217" DIA Polyimide Film Pick & Place Pad

-TR  
= Tape and Reel

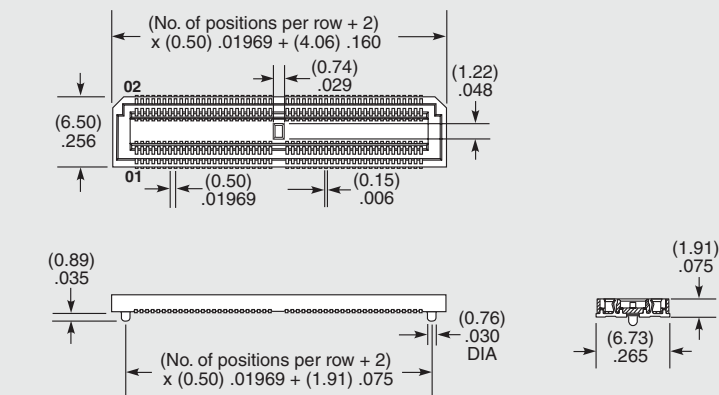


-010, -020, -030, -040, -050

-G  
= 10 μ" (0.25 μm) Gold

-K  
= (7.50 mm) .295" DIA Polyimide Film Pick & Place Pad

-TR  
= Tape and Reel



Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.